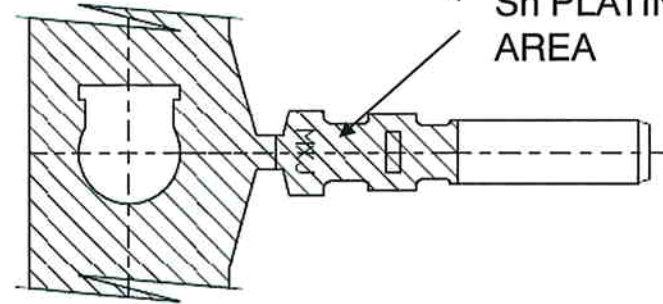
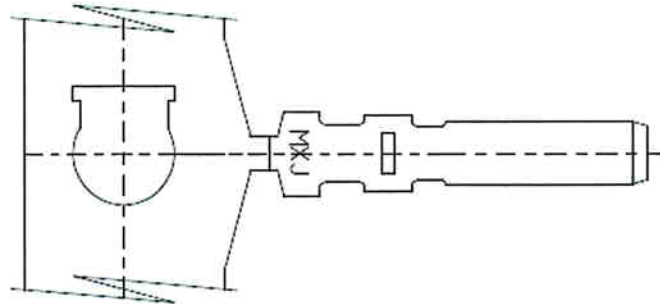
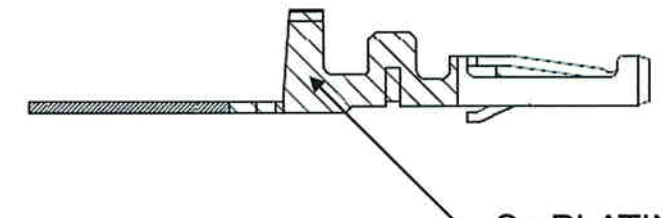
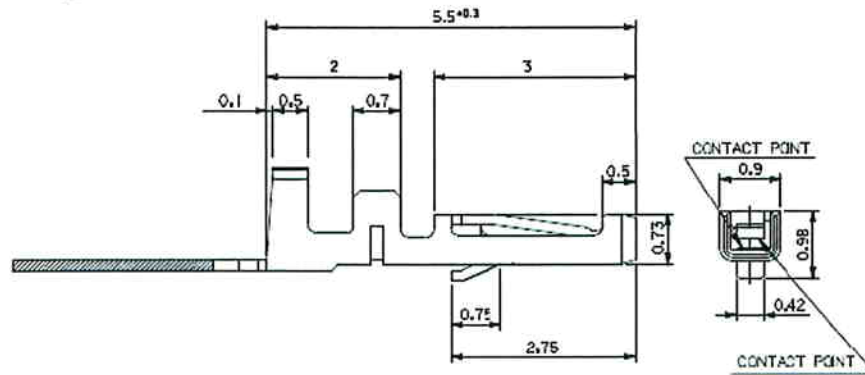
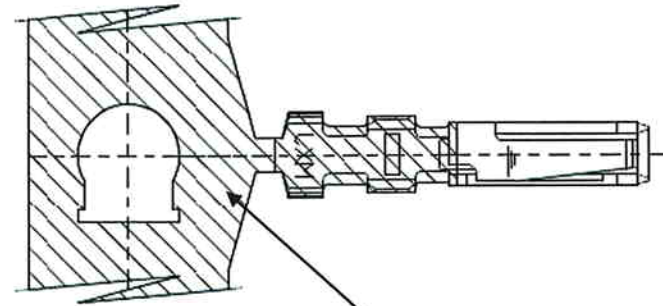
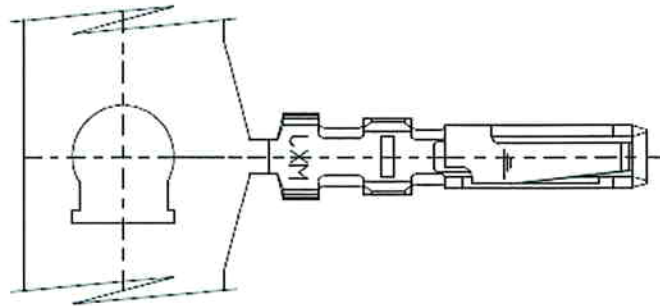


50641-8041 1.25 WB CRIMP REC.  
CHANGED PLATING DRAWING

2011/05/10  
MOLEX MPD

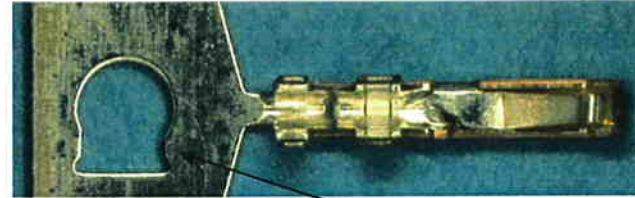


CURRENT PRODUCT  
Au:0.2μmMIN.  
Ni(UNDER PLATE):1.5μmMIN.



PRE-PLATED PRODUCT  
Au(CONTACT AREA):0.2μmMIN.  
Sn(HATCHED AREA):0.9μmMIN.  
Ni(UNDER PLATE):1.0μmMIN.

50641-8041 1.25 WB CRIMP REC.  
CHANGED PLATING PHOTOGRAPH



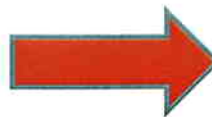
Sn PLATING  
AREA



Sn PLATING  
AREA



CURRENT PRODUCT  
Au:0.2 $\mu$ mMIN.  
Ni(UNDER PLATE):1.5 $\mu$ mMIN.



PRE-PLATED PRODUCT  
Au(CONTACT AREA):0.2 $\mu$ mMIN.  
Sn(HATCHED AREA):0.9 $\mu$ mMIN.  
Ni(UNDER PLATE):1.0 $\mu$ mMIN.